## **BGA Heat Sink - High Performance**

**Device Specific - NXP** 





\*Image above is for illustration purpose only

ATS Part#: ATS-59009-C1-R0

62.00 x 52.00 x 13.00 mm BGA Heat Sink - High Performance Device Specific - NXP Description:

Heat Sink Type: NXP

Heat Sink Attachment: maxiGRIP

Equivalent Part Number: ATS-59009-C2-R0

## **Features & Benefits**

- Designed for flip-chip processors such as NXP MPCs
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Comes preassembled with high performance, thermal interface material

## **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.2 °C/W	2.6 °C/W	2.1 °C/W	1.9 °C/W	1.7 °C/W	1.5 °C/W	1.4 °C/W
	Ducted Flow	1.8	N/A	N/A	N/A	N/A	N/A	N/A

## **Product Detail**





